

SCOPE: MICROPROCESSOR SUPERVISORY CIRCUITS

| <u>Device Type</u> | <u>Generic Number</u> |
|--------------------|-----------------------|
| 01 | MAX690(x)/883B |
| 02 | MAX691(x)/883B |
| 03 | MAX692(x)/883B |
| 04 | MAX693(x)/883B |
| 05 | MAX694(x)/883B |
| 06 | MAX695(x)/883B |

Case Outline(s). The case outlines shall be designated in Mil-Std-1835 and as follows:

| <u>Outline Letter</u> | <u>Mil-Std-1835</u> | <u>Case Outline</u> | <u>Package Code</u> |
|-----------------------|------------------------|----------------------|---------------------|
| MAXIM SMD | | | |
| JA P | GDIP1-T08 or CDIP2-T08 | 8 LEAD CERDIP | J08 |
| JE E | GDIP1-T16 or CDIP2-T16 | 16 LEAD CERDIP | J16 |
| FB X | CDFP3-F10 | 10 LEAD Flatpack | F10 |
| LP 2 | CQCC1-N20 | 20 Pin Leadless Chip | L20 |

Absolute Maximum Ratings

Terminal Voltage (with respect to GND)

| | |
|--------------------------------------|-----------------------------------|
| V _{CC} | -0.3V to +6.0V |
| V _{BATT} | -0.3V to +6.0V |
| All other Inputs $\frac{1}{2}$ | -0.3V to (V _{OUT} +0.5V) |

Input Current

| | |
|-------------------------|-------|
| V _{CC} | 200mA |
| V _{BATT} | 50mA |
| GND | 20mA |

Output Current

| | |
|-------------------------|-------------------------|
| V _{OUT} | Short-circuit protected |
| All other outputs | 20mA |

Rate of Rise, V_{CC}, V_{BATT} 100V/μs

Lead Temperature (soldering, 10 seconds) +300°C

Storage Temperature -65°C to +160°C

Continuous Power Dissipation T_A=+70°C

8 lead CERDIP(derate 8.0mW/°C above +70°C) 640mW

16 lead CERDIP(derate 10.0mW/°C above +70°C) 800mW

10 lead Flatpack(derate 5.3mW/°C above +70°C) 421mW

20 lead LCC(derate 9.1mW/°C above +70°C) 727mW

Junction Temperature T_J +150°C

Thermal Resistance, Junction to Case, Θ_{JC}:

| | |
|---|--------|
| Case Outline 8 lead CERDIP..... | 55°C/W |
| Case Outline 16 lead CERDIP..... | 50°C/W |
| Case Outline 10 lead Flatpack | 85°C/W |
| Case Outline 20 leadless Chip carrier | 20°C/W |

Thermal Resistance, Junction to Ambient, Θ_{JA}:

| | |
|---|---------|
| Case Outline 8 lead CERDIP..... | 125°C/W |
| Case Outline 16 lead CERDIP..... | 100°C/W |
| Case Outline 10 lead Flatpack | 190°C/W |
| Case Outline 20 leadless Chip carrier | 110°C/W |

NOTE 1: The input voltage limits on PFI and WDI may be exceeded if the input current is less than 10mA.

Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Recommended Operating Conditions

| | |
|---|-----------------|
| Ambient Operating Range (T_A) | -55°C to +125°C |
| Supply Voltage Range (V_{CC}) DASH 03 & 04 | +4.5V to +5.5V |
| Supply Voltage Range (V_{CC}) DASH 01, 02, 05, 06 | +4.75V to +5.5V |

TABLE 1. ELECTRICAL TESTS:

| TEST | Symbol | CONDITIONS | | Group A Subgroup | Device type | Limits Min | Limits Max | Units | | |
|---|------------------------|--|----------|------------------|-----------------|------------------------|----------------|----------|----|-----|
| | | -55 °C ≤ T _A ≤ +125°C 2/ Unless otherwise specified | | | | | | | | |
| BATTERY-BACKUP SWITCHING | | | | | | | | | | |
| Operating Voltage Range | V _{CC} | | 1,2,3 | | 01,02, 05,06 | 4.75 | 5.5 | V | | |
| | | | | | 03,04 | 4.5 | 5.5 | | | |
| Operating Voltage Range | V _{BATT} | | 1,2,3 | | 01,02, 05,06 | 2.0 | 4.25 | V | | |
| | | | | | 03,04 | 2.0 | 4.0 | | | |
| Output Voltage | V _{OUT} | I _{OUT} =1mA | 1,2,3 | | All | V _{CC} -0.3 | | V | | |
| | | I _{OUT} =50mA | | | | V _{CC} -0.5 | | | | |
| Output Voltage-Battery-Backup Mode | BATT _{OUT} | I _{OUT} =250μA, V _{CC} <V _{BATT} -0.2V | 1,2,3 | | All | V _{BATT} -0.1 | | V | | |
| Supply Current (Excludes I _{OUT}) | I _{CC} | I _{OUT} =1mA | 1 2,3 | | All | | 5 7 | mA | | |
| | | I _{OUT} =50mA | 1 2,3 | | | | 10 15 | | | |
| Supply Current in Battery-Backup Mode | I _{BATT} | V _{CC} =0V, V _{BATT} =2.8V | 1 2,3 | | All | | 1 10 | μA | | |
| Battery Standby Current | BATT SBI | 5.5V>V _{CC} >V _{BATT} +1V +=Discharge, -=Charge | 1 2,3 | | All | -0.10 -1.00 | +0.02 +0.02 | μA | | |
| Battery-Switchover, Threshold, V _{CC} to V _{BATT} | BATT SW _{TH} | Power-Up or Power-Down | 1,2,3 | | All | -200 | +200 | mV | | |
| BATT ON Output Voltage | BATT ON _{OUT} | I _{SINK} =3.2mA | 1,2,3 | | 02,04,06 | | 0.4 | V | | |
| BATT ON Output Short-Circuit Current | BATT ON _{IOS} | BATT ON = V _{OUT} BATT ON =0V Source Current | 1,2,3 | | 02,04,06 | 0.1 | 60 | mA μA | | |
| | | | | | | | 25 | | | |
| RESET AND WATCHDOG TIMING | | | | | | | | | | |
| Reset Voltage Threshold | R _{TH} | | 1,2,3 | | 01,02, 05,06 | 4.5 | 4.75 | V | | |
| | | | | | 03,04 | 4.25 | 4.5 | | | |
| Reset Threshold Hysteresis | RT _{HH} | | 1,2,3 | | All | | 250 | mV | | |
| Reset Timeout Delay | R _{DEL} | OSC SEL High, V _{CC} =5V | 9 | | | | 35 | 70 | ms | |
| | | | 10,11 | | | | 01,02 03,04 | 31 | | 78 |
| | | | 9 | | | | 05,06 | 140 | | 280 |
| | | | 10,11 | | | | | 126 | | 310 |

| TEST | Symbol | CONDITIONS | | Group A Subgroup | Device type | Limits Min | Limits Max | Units |
|--|--------------------|--|--|------------------|-------------|--------------|--------------|--------------|
| | | -55 °C ≤ T _A ≤ +125 °C 2/ Unless otherwise specified | | | | | | |
| Watchdog Timeout Period, Internal Oscillator | WD _{INT} | Long Period, V _{CC} =5V | | 9 10,11 | All | 1.00 0.90 | 2.25 2.42 | sec |
| | | Short Period, V _{CC} =5V | | 9 10,11 | | 70 62 | 140 154 | ms |
| Watchdog Timeout Period, External Clock | WD _{EXT} | Long Period | | 9 10,11 | 02,04,06 | 3840 | 4097 | Clock Cycles |
| | | Short Period | | 9 10,11 | 02,04,06 | 768 | 1025 | |
| Minimum WDI Input Pulse Width | WDI _{PW} | V _{IL} =0.4V, V _{IH} =V _{CC} (0.8) | | 9 10,11 | All | 200 300 | | ns |
| RESET Output Voltage High | R _{VOH} | I _{SOURCE} =1μA, V _{CC} =5V | | 1,2,3 | All | 3.5 | | V |
| RESET Output Voltage Low | R _{VOL} | I _{SINK} =1.6mA, V _{CC} =4.25V | | 1 | All | | 0.4 | V |
| | | I _{SINK} =800μA, V _{CC} =4.25V | | 2,3 | | | 0.4 | |
| LOWLINE Output Voltage High | LL _{VOH} | I _{SOURCE} =1μA, V _{CC} =5V | | 1,2,3 | 02,04,06 | 3.5 | | V |
| LOWLINE Output Voltage Low | LL _{VOL} | I _{SINK} =1.6mA, V _{CC} =4.25V | | 1 | 02,04,06 | | 0.4 | V |
| | | I _{SINK} =800μA, V _{CC} =4.25V | | 2,3 | | | 0.4 | |
| WDO Output Voltage High | WDO _{VOH} | I _{SOURCE} =1μA, V _{CC} =5V | | 1,2,3 | All | 3.5 | | V |
| WDO Output Voltage Low | WDO _{VOL} | I _{SINK} =1.6mA, V _{CC} =4.25V | | 1 | 02,04,06 | | 0.4 | V |
| | | I _{SINK} =800μA, V _{CC} =4.25V | | 2,3 | | | 0.4 | |
| Reset Output Voltage High | R _{VOH} | I _{SOURCE} =1μA, V _{CC} =5V | | 1,2,3 | 02,04,06 | 3.5 | | V |
| Reset Output Voltage Low | R _{VOL} | I _{SINK} =1.6mA | | 1 | 02,04,06 | | 0.4 | V |
| | | I _{SINK} =800μA | | 2,3 | | | 0.4 | |
| Output Short-Circuit Current | I _{OS} | RESET=0V | | 1,2,3 | All | 1 | 25 | μA |
| | | RESET, RESET, WDO, LL | | | 02,04,06 | 1 | 25 | |
| WDI Input Threshold Logic Low | WDI _{VIL} | V _{CC} =5V NOTE 3 | | 1 2,3 | All | | 0.8 0.4 | V |
| WDI Input Threshold Logic High | WDI _{VIH} | V _{CC} =5V NOTE 3 | | 1 2,3 | All | 3.5 4.0 | | V |
| WDI Input Current | WDI _{IN} | WDI=V _{OUT} | | 1 2,3 | All | | 50 80 | μA |
| | | WDI=0V | | 1 2,3 | | -50 -80 | | |

| TEST | Symbol | CONDITIONS | | Group A Subgroup | Device type | Limits Min | Limits Max | Units |
|--|----------------------|--|--|------------------|-------------|------------------------|------------|-------|
| | | -55 °C ≤ T _A ≤ +125 °C 2/ Unless otherwise specified | | | | | | |
| POWER-FAIL DETECTOR | | | | | | | | |
| PFI Input Threshold | PFI _{VTH} | V _{CC} =5V | | 1,2,3 | All | 1.2 | 1.4 | V |
| PFI Input Current | PFI _{IN} | | | 1,2,3 | All | -25 | 25 | nA |
| PFO Output Voltage High | PFO _{VOH} | I _{SOURCE} =1μA, V _{CC} =5V | | 1,2,3 | All | 3.5 | | V |
| PFO Output Voltage Low | PFO _{VOL} | I _{SINK} =3.2mA | | 1 | All | | 0.4 | V |
| | | I _{SINK} =1.6mA | | 2,3 | | 0.4 | | |
| PFO Short-Circuit Source Current | PFO _{IOS} | PFI=V _{IH} , PFO=0V | | 1,2,3 | All | 1.0 | 25 | μA |
| CHIP-ENABLE GATING | | | | | | | | |
| CE IN Thresholds Logic Low | CE _{VIL} | | | 1 | 02,04,06 | | 0.8 | V |
| | | | | 2,3 | | 0.4 | | |
| CE IN Thresholds Logic High | CE _{VIH} | | | 1 | 02,04,06 | 3.0 | | V |
| | | | | 2,3 | | 4.0 | | |
| CE IN Pull-Up Current | CE _{INPI} | | | 1,2,3 | 02,04,06 | 1.0 | 25 | μA |
| CE OUT Output Voltage High | CE _{VOH} | I _{SOURCE} =3.0mA, V _{CC} =4.75V | | 1,2,3 | 02,04,06 | V _{OUT} -1.5 | | V |
| | | I _{SOURCE} =1μA, V _{CC} =0V | | | | V _{OUT} -0.05 | | |
| CE Output Voltage Low | CE _{VOL} | I _{SINK} =3.2mA | | 1 | 02,04,06 | | 0.4 | V |
| | | I _{SINK} =1.6mA | | 2,3 | | 0.4 | | |
| CE Propagation Delay | t _{PDCE} | V _{CC} =5V | | 9 | 02,04,06 | | 200 | ns |
| | | | | 10,11 | | 300 | | |
| OSCILLATOR | | | | | | | | |
| OSC IN Input Current Pull-Up | OSCI _{IN} | | | 1,2,3 | 02,04,06 | | 25 | μA |
| OSC SEL Input Pull-Up Current | OSC _{SELIN} | | | 1,2,3 | 02,04,06 | 1 | 25 | μA |
| OSC IN Frequency Range | OSC _{INfrq} | OSC SEL=0V | | 9,10,11 | 02,04,06 | 0 | 250 | kHz |
| OSC IN Frequency with External Capacitor | OSC _{IN} | OSC SEL=0V, COSC=47pF NOTE 4 | | 9 | 02,04,06 | 4 | | kHz |

NOTE 2: V_{CC}=full operating range, V_{BATT}=+2.8V.

NOTE 3: WDI is guaranteed to be in the mid-level (inactive) state if WDI is floating and V_{CC} is in the operating range. WDI is internally biased to 38% of V_{CC} with an impedance of approximately 125kΩ

NOTE 4: Typical for design purposes only but not tested. Guaranteed for SMD 5962-90711 and 5962-90712.

| | Package | ORDERING INFORMATION: | SMD NUMBER |
|----|-----------------|-----------------------|-----------------|
| 01 | 8 pin CERDIP | MAX690MJA/883B | 5962-9071201MPA |
| 01 | 10 pin Flatpack | MAX690MFB/883B | 5962-9071201MXC |
| 01 | 20 pin LCC | MAX690MLP/883B | 5962-9071201M2C |
| 02 | 8 pin CERDIP | MAX691MJA/883B | 5962-9071101MPA |
| 02 | 20 pin LCC | MAX691MLP/883B | 5962-9071101M2C |
| 03 | 8 pin CERDIP | MAX692MJA/883B | 5962-9071202MPA |
| 03 | 10 pin Flatpack | MAX692MFB/883B | 5962-9071202MXC |
| 03 | 20 pin LCC | MAX692MLP/883B | 5962-9071202M2C |
| 04 | 8 pin CERDIP | MAX693MJA/883B | 5962-9071102MPA |
| 04 | 20 pin LCC | MAX693MLP/883B | 5962-9071102M2C |
| 05 | 8 pin CERDIP | MAX694MJA/883B | 5962-9071203MPA |
| 05 | 10 pin Flatpack | MAX694MFB/883B | 5962-9071203MXC |
| 05 | 20 pin LCC | MAX694MLP/883B | 5962-9071203M2C |
| 06 | 8 pin CERDIP | MAX695MJA/883B | 5962-9071103MPA |

TERMINAL CONNECTIONS:

| | MAX690/692/694 | MAX690/692/694 | MAX690/692/694 | MAX691/693/695 | MAX691/693 |
|----|-------------------|-------------------|-------------------|-------------------|-------------------|
| | J8 | F10 | L20 | J16 | L20 |
| 1 | V _{OUT} | V _{OUT} | NC | V _{BATT} | NC |
| 2 | V _{CC} | V _{CC} | V _{BATT} | V _{OUT} | V _{BATT} |
| 3 | GND | GND | V _{OUT} | V _{CC} | V _{OUT} |
| 4 | PFI | NC | V _{CC} | GND | V _{CC} |
| 5 | _____ | PFI | GND | BATT ON | GND |
| | PFO | | | | |
| 6 | WDI | _____ | NC | _____ | NC |
| | | PFO | | LOWLINE | |
| 7 | _____ | WDI | NC | OSC IN | BATT ON |
| | RESET | | | | |
| 8 | V _{BATT} | NC | NC | OSC SEL | _____ |
| | | | | | LOWLINE |
| 9 | | _____ | NC | PFI | OSC IN |
| | | RESET | | | OSC SEL |
| 10 | | V _{BATT} | NC | _____ | |
| | | | | PFO | |
| 11 | | | NC | WDI | NC |
| 12 | | | PFI | _____ | PFI |
| | | | | CE OUT | |
| 13 | | | _____ | _____ | _____ |
| | | | PFO | CE IN | PFO |
| 14 | | | WDI | _____ | WDI |
| | | | | WDO | |
| 15 | | | NC | _____ | _____ |
| | | | | RESET | CE OUT |
| 16 | | | NC | RESET | NC |
| 17 | | | NC | | _____ |
| | | | | | CE IN |
| 18 | | | NC | | _____ |
| | | | | | WDO |
| 19 | | | _____ | | _____ |
| | | | RESET | | RESET |
| 20 | | | NC | | RESET |

QUALITY ASSURANCE

Sampling and inspection procedures shall be in accordance with MIL-Prf-38535, Appendix A as specified in Mil-Std-883.

Screening shall be in accordance with Method 5004 of Mil-Std-883. Burn-in test Method 1015:

1. Test Condition, A, B, C, or D.
2. TA = +125°C minimum.
3. Interim and final electrical test requirements shall be specified in Table 2.

Quality conformance inspection shall be in accordance with Method 5005 of Mil-Std-883, including Groups A, B, C, and D inspection.

Group A inspection:

1. Tests as specified in Table 2.
2. Selected subgroups in Table 1, Method 5005 of Mil-Std-883 shall be omitted.

Group C and D inspections:

- a. End-point electrical parameters shall be specified in Table 1.
- b. Steady-state life test, Method 1005 of Mil-Std-883:
 1. Test condition A, B, C, D.
 2. TA = +125°C, minimum.
 3. Test duration, 1000 hours, except as permitted by Method 1005 of Mil-Std-883.

TABLE 2. ELECTRICAL TEST REQUIREMENTS

| Mil-Std-883 Test Requirements | Subgroups per Method 5005, Table 1 |
|--|---------------------------------------|
| Interim Electric Parameters Method 5004 | 1 |
| Final Electrical Parameters Method 5005 | 1*, 2, 3, 9, 10, 11 |
| Group A Test Requirements Method 5005 | 1, 2, 3, 9, 10, 11 |
| Group C and D End-Point Electrical Parameters Method 5005 | 1 |

* PDA applies to Subgroup 1 only.